

Making the Most of Our Failures

**NM Tech Grad Seminar
Jan. 25, 2018**

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Sandia National Laboratories is a multimission laboratory managed and operated by National Technology and Engineering Solutions of Sandia, LLC., a wholly owned subsidiary of Honeywell International, Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA-0003525.



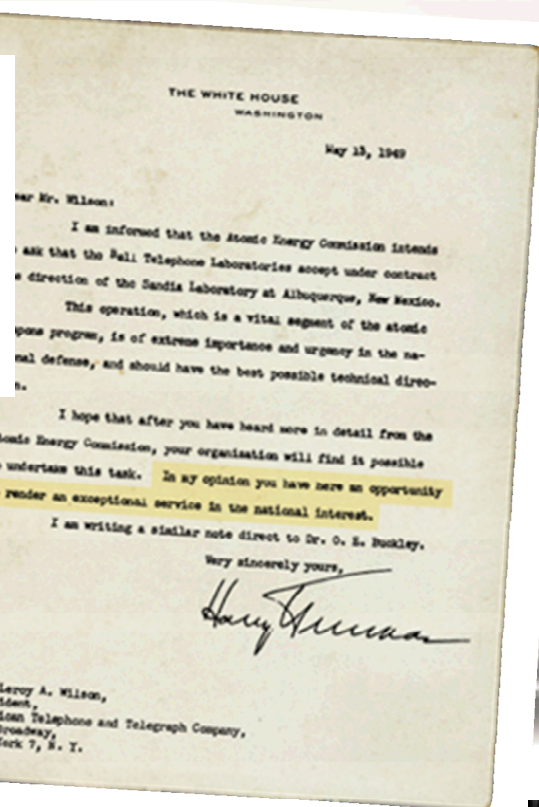
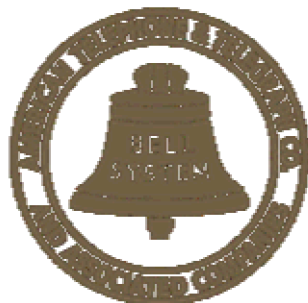


Outline

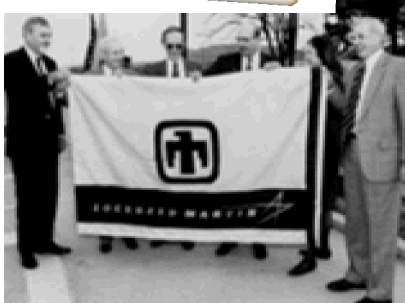
- Sandia National Labs
 - Overview
 - Education and Sandia Career
 - Materials and Process Sciences Center
 - Power Sources Technology Group
- Failure Ingredients
- Failure Examples
- Making the Most of Our Failures

Sandia's History: Exceptional service in the national interest

- July 1945: Los Alamos creates Z Division
- Nonnuclear communications engineering
- November 1, 1949: Sandia Laboratory established



to undertake this task. In my opinion you have here an opportunity to render an exceptional service in the national interest.



Governance of Sandia Laboratories

Sandia Corporation

- AT&T: 1949–1993
- Martin Marietta: 1993–1995
- Lockheed Martin: 1995–2017
- National Technology and Engineering Solutions of Sandia, LLC, a wholly owned subsidiary of Honeywell International Inc.: 2017-present
- Government owned, contractor operated

Federally funded
research and development center



Sandia Sites

Albuquerque, New Mexico



Livermore, California



Kauai, Hawaii



*Waste Isolation Pilot Plant,
Carlsbad, New Mexico*



*Pantex Plant,
Amarillo, Texas*

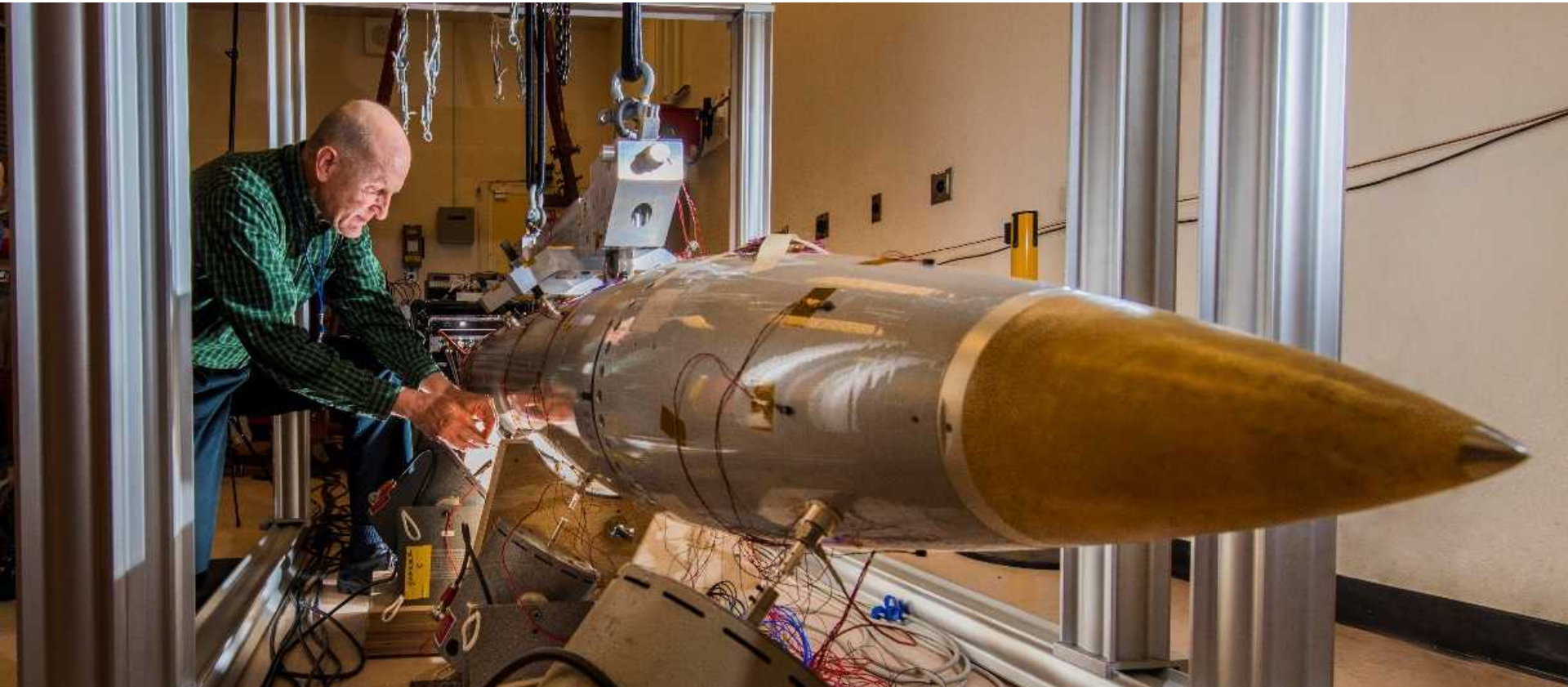


*Tonopah,
Nevada*





Sandia develops advanced technologies to ensure global peace



Sandia Addresses National Security Challenges

1950s

Nuclear weapons

Production and
manufacturing
engineering



1960s

Development
engineering

Vietnam conflict



1970s

Multiprogram
laboratory

Energy crisis



1980s

Missile defense
work

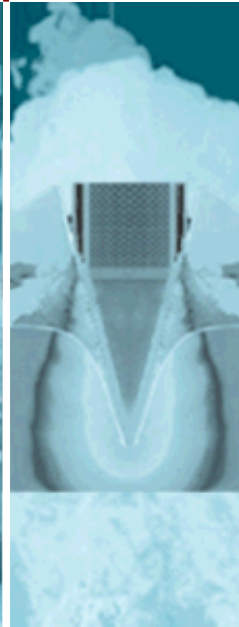
Cold War



1990s

Post-Cold War
transition

Stockpile
stewardship



2000s

START
Post 9/11

National security



2010s

LEPs
Cyber, biosecurity
proliferation

Evolving national
security challenges





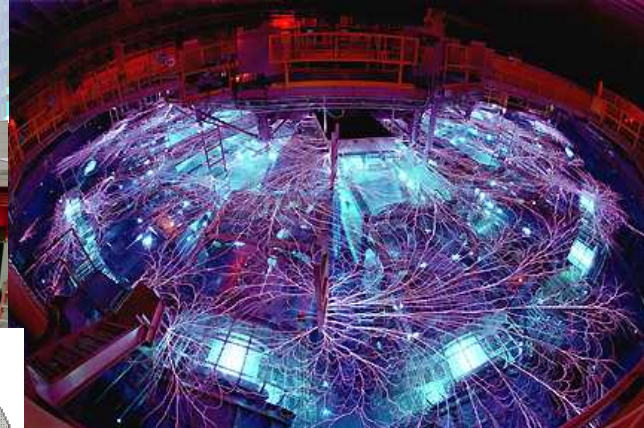
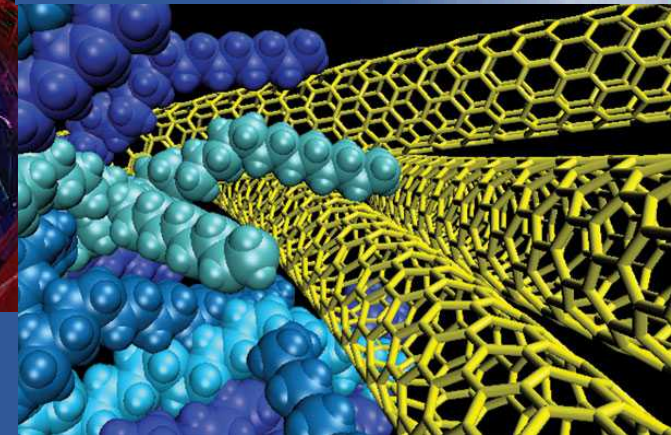
Sandia's Science and Technology Framework

Strong research foundations play a differentiating role in our mission delivery

Computing & Information Sciences

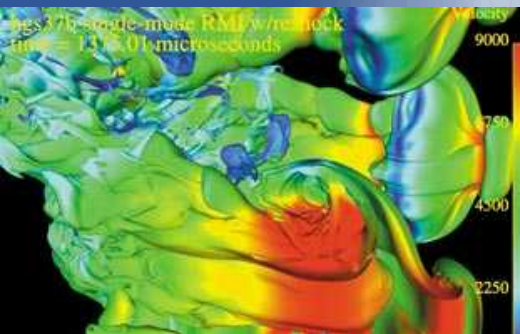


Materials Sciences



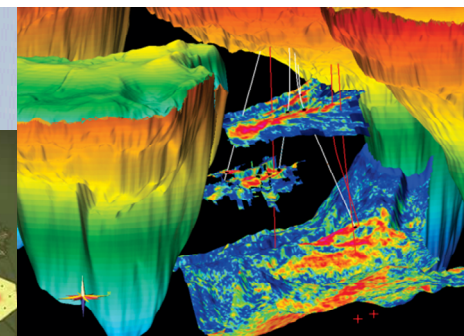
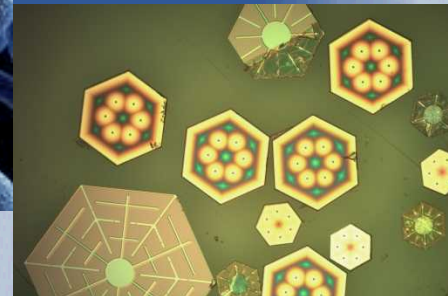
Radiation Effects & High Energy Density Science

Engineering Sciences



Bioscience

Nanodevices & Microsystems



Geoscience



Education and Sandia Career

Education

McMaster University – Ceramic Engineering (BS, 1984)

Penn State – Ceramic Science (MS, 1987 & PhD, 1990)

Career

Center 1800 – Materials & Process Sciences (1990-2015)

Group 1850 – Materials Aging and Reliability

Dept. 1852 – Materials Reliability

Center 2500 – Component Sci., Engr. & Production (2015-2018)

Group 2540 – Power Sources Technology Group

Dept. 2547 – Power Sources Component Development



Materials and Process Sciences R&D

Synthesis and Processing

Characterization

Performance and Reliability

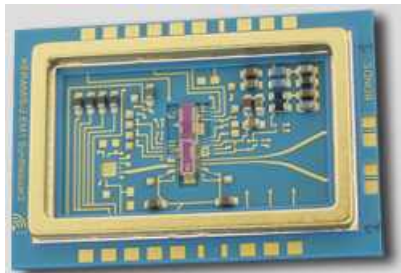
– Mechanical Performance

- Ductile Materials
- Brittle Materials

Brittle Material Containing Components

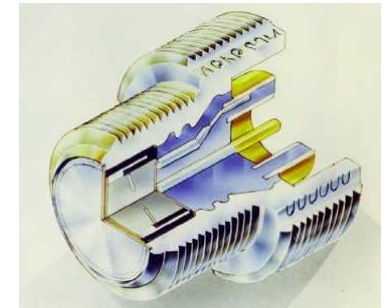
Materials

- 94% and 96% Al_2O_3
- Mo - Al_2O_3 Cermets
- Bulk Glasses and Glass Ceramics
- Glass Fibers
- Ceramic Ferrites
- PZT (lead zirconate titanate)
- PMN-PT (lead magnesium niobate - zirconate titanate)
- Barium Titanate
- ZnO Varistor Materials
- Polysilicon
- LTCC (low temp co-fired ceramic)



Components (Sandia and Externally Produced)

- Batteries and other Power Sources
- Slim Loop Ferroelectrics
- Rolamite Switches
- Neutron Sources
- Safe Enable Wheels
- Stronglinks
- Voltage Bars
- Current Stacks
- Discoidal Capacitors
- Electronic Substrates
- Clocks
- Photo Diodes
- Connectors





Sandia Products

Microelectronics

Explosives

Switch Tubes

Capacitors

Neutron Sources

Power Sources

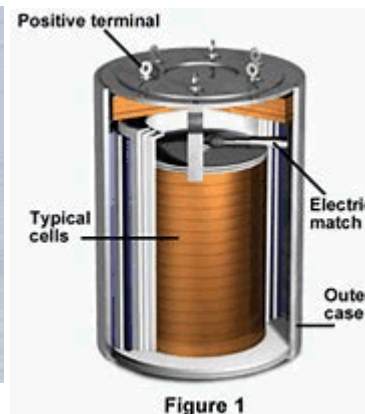
- Thermal batteries
- Li primary and Li ion batteries
- Thermoelectrics

Power Sources Technology Group (PSTG)

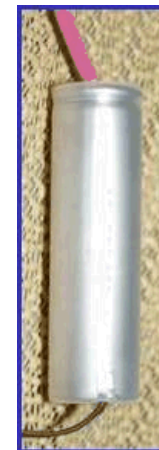
- Scientific and engineering solutions to meet national needs for power sources in nuclear weapons, advanced conventional weapons, energy, and security applications.
- Primary customers are Department of Energy, Department of Defense, other government agencies, and industry.
- We are designated as the DOE back-up thermal battery production capability.



Production Dry-Room



Thermal, Li Primary, and Li Ion Batteries



Cell Prototyping



Battery Testing Including Battery Abuse Testing

Failure in Brittle Materials





Strength is Flaw Size Dependent for a Brittle Material

$$\text{When } \sigma_a \text{ or } \sigma_r > \sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$$

Where:

σ_f = fracture strength

K_{IC} = fracture toughness or critical stress intensity

c = flaw size

Y = geometrical factor

σ_a = applied stress

σ_r = residual stress

Ingredients for Brittle Material Failure

When σ_{applied} > or residual $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$

Poor Design - Excessive stress

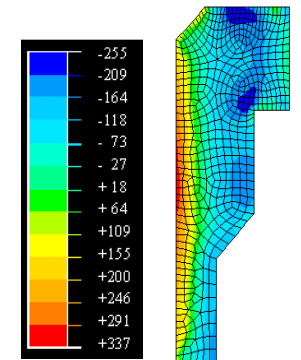
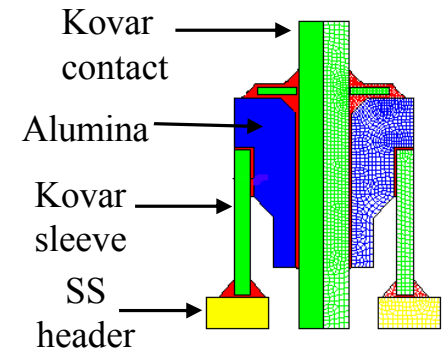
- Excessive applied/local stresses
- Materials combinations and/or processing that lead to excessive residual stress

Presence or introduction of defects

- Intrinsic microstructural features
- Processing related
- Machining, in-service damage

Material degradation

- Environmental effects, decrease in K_{IC}
- Increase in flaw size - subcritical crack growth

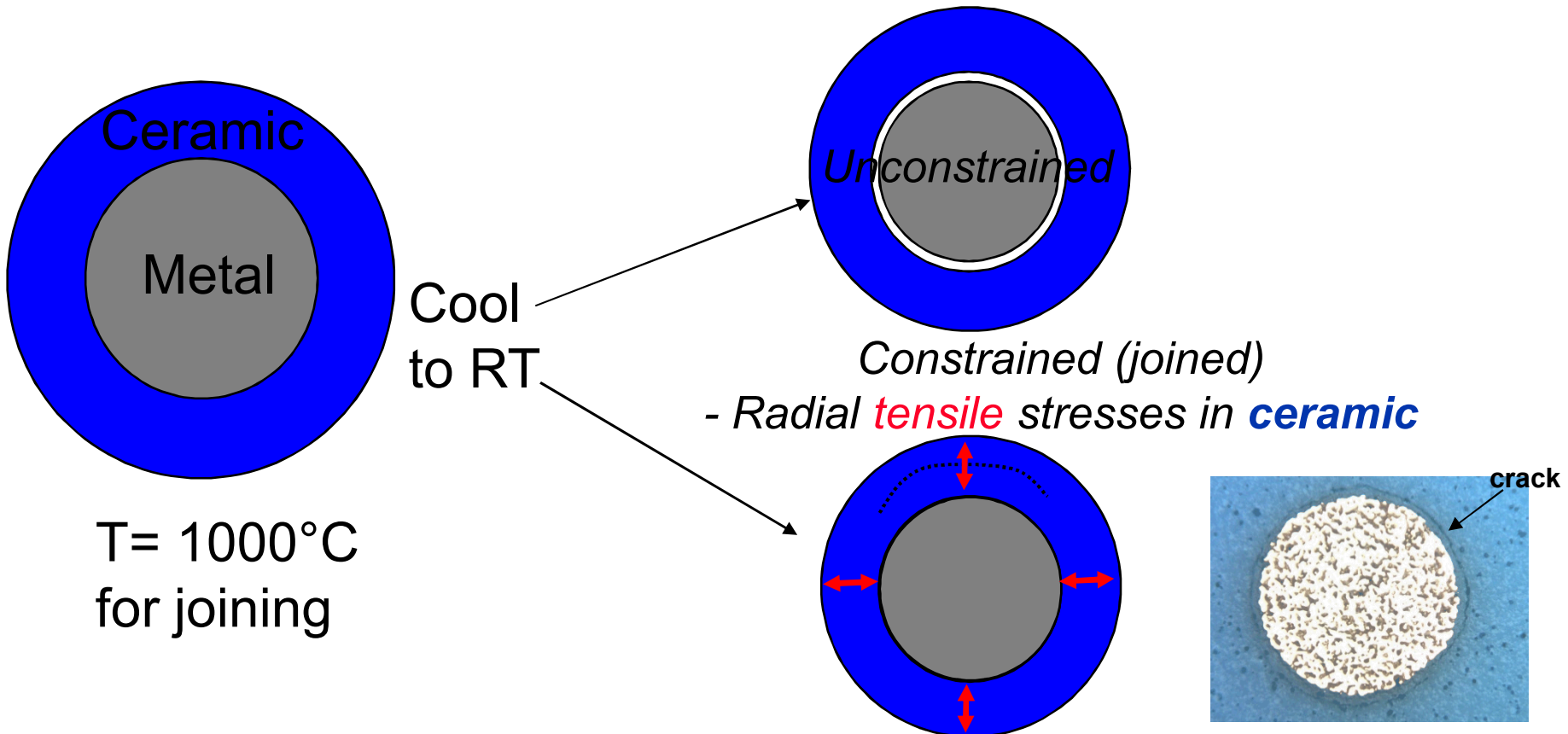


max. prin. stress (MPa) in alumina

All of the above!

Thermal and Residual Stresses Can Produce Cracking of a Glass or Ceramic

- Uneven cooling produces thermal stresses
- Joining dissimilar materials produces residual stresses because of thermal expansion (CTE) mismatch



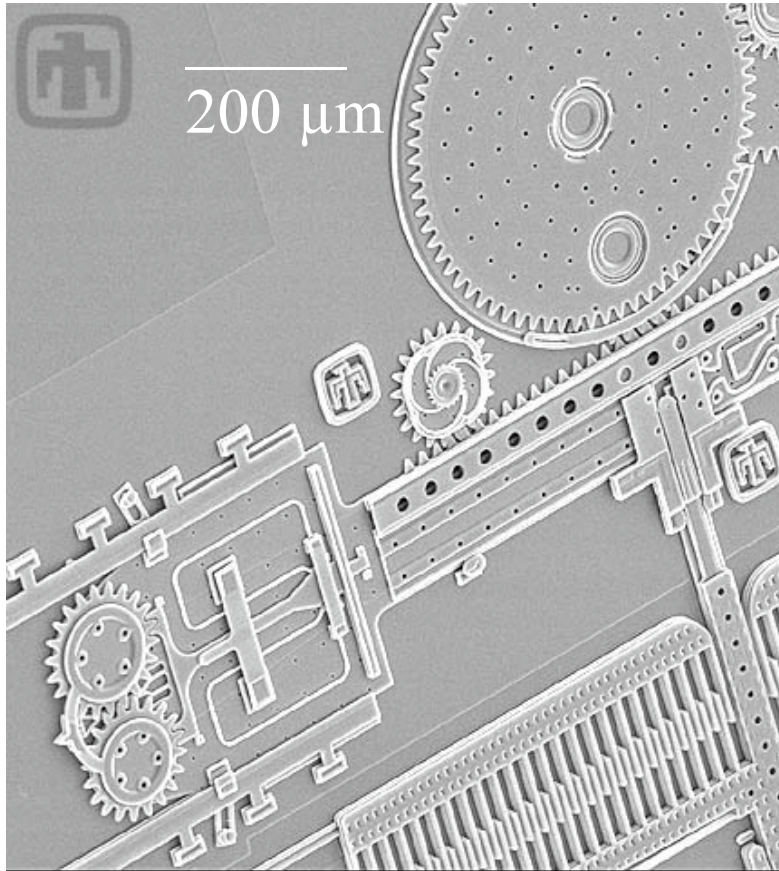


Brittle Materials Failure Examples

- MEMS polysilicon (Buchheit and Boyce)
- LTCC's with vias (Tandon, Monroe, Newton, Ewsuk)
- LTCC strength samples (Tandon, Monroe, Newton, Roth)
- ZnO varistors (Watson, Lockwood, and Diantonio)
- Pressurized sulfuric acid tank from industry (many)
- Ni lead failure (many)

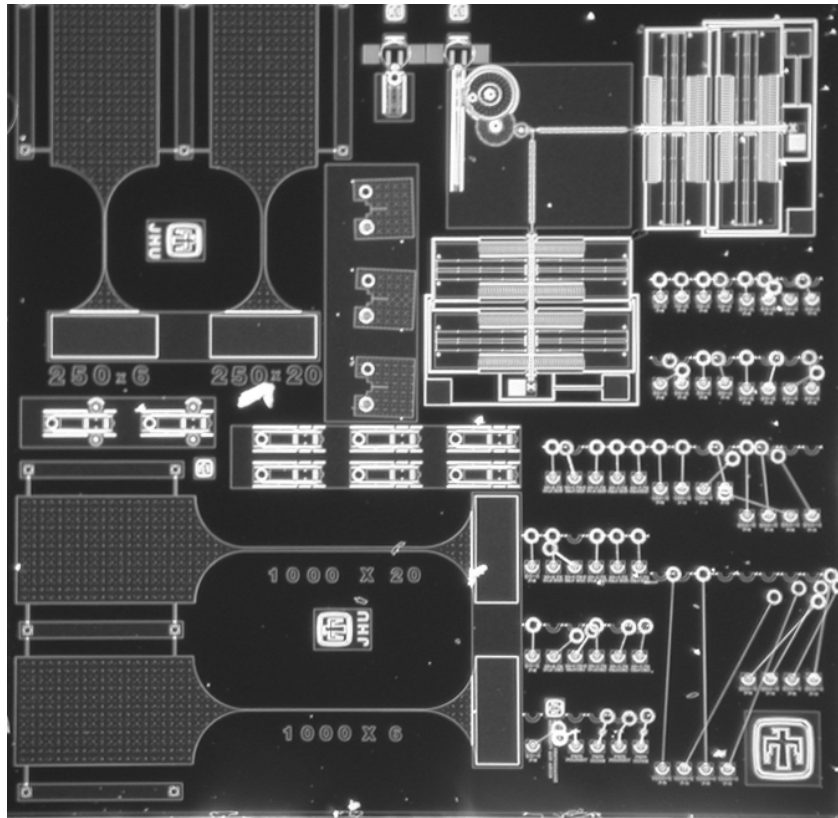
Fracture Strength Testing and Failure Origins for Polysilicon MEMS Materials

24-bit lock with 24-bit path, drive gears, anti-reversing gears, meshing gears, etc.

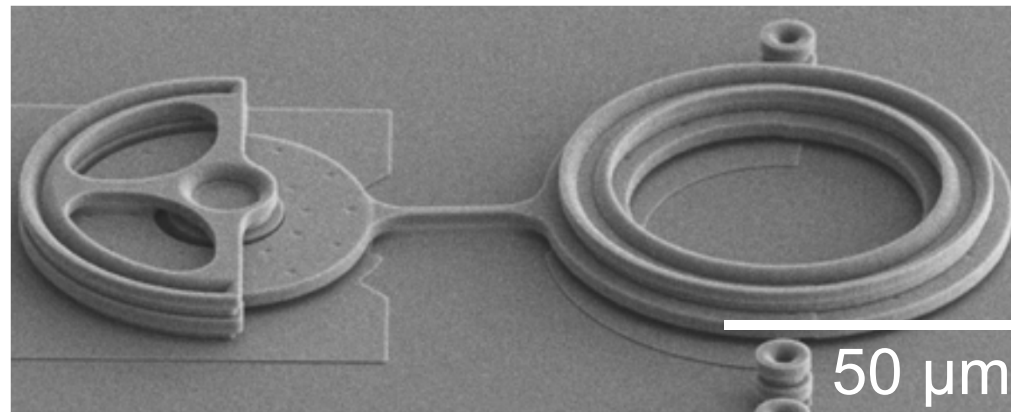


- Modest structural properties ($K_{IC}=1.0-1.4 \text{ MPa}\sqrt{\text{m}}$)
- High degree of reactivity with oxygen, water and other reagents

Polysilicon Mechanical Testing Samples Fabricated Directly on the Die



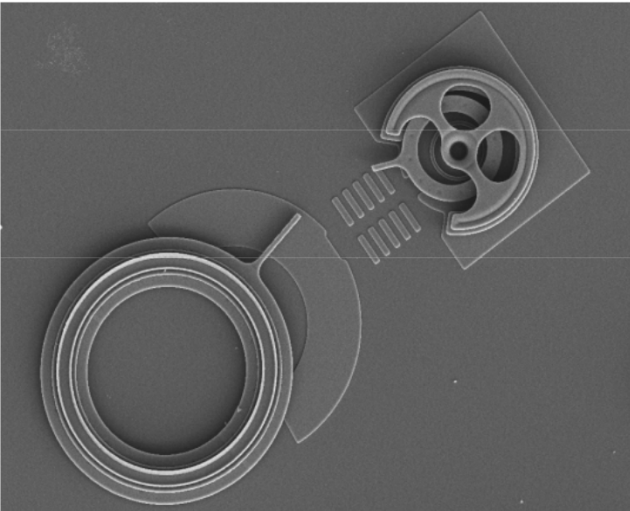
Pull-tab tensile strength sample.



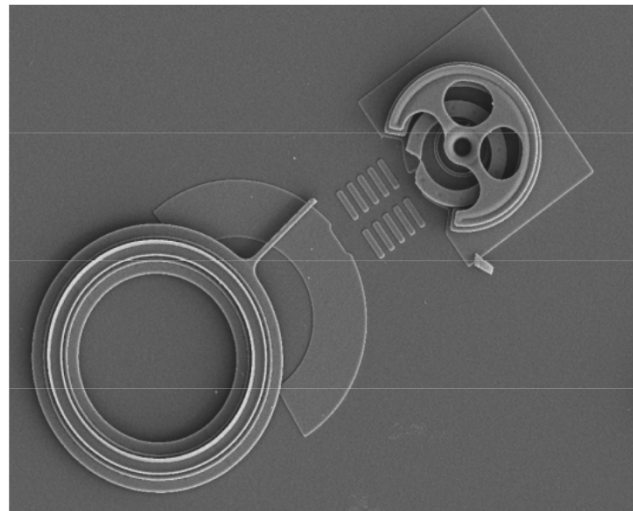


2 of 3 Failure Modes for 48 First Generation Polysilicon Samples Due to Pull-Tab Design

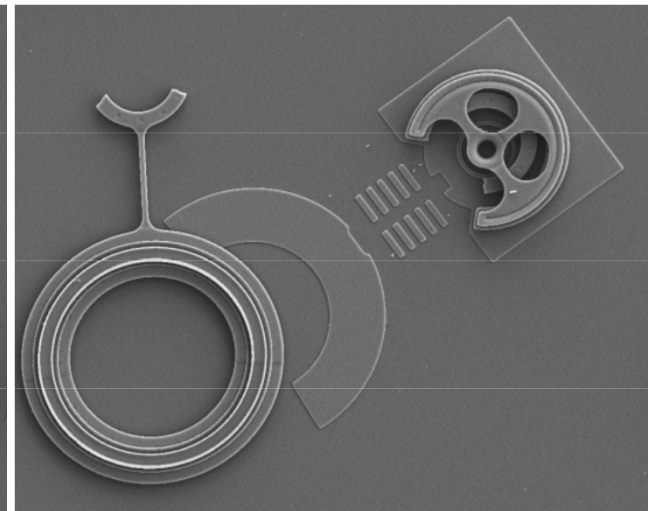
Average $\sigma_f = 2.24 \text{ GPa} \pm 0.35$



7 Strongest

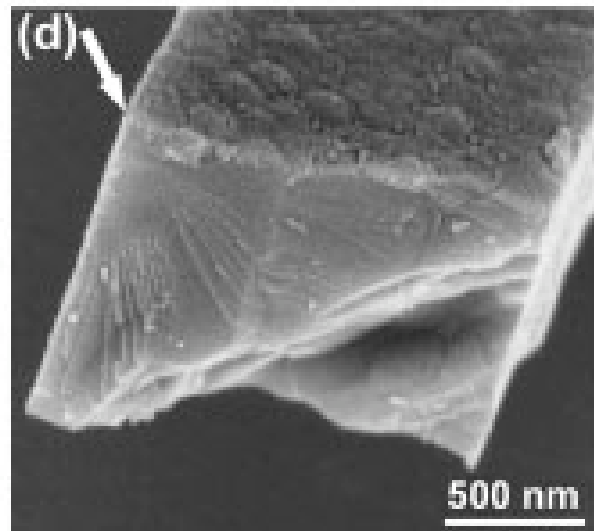
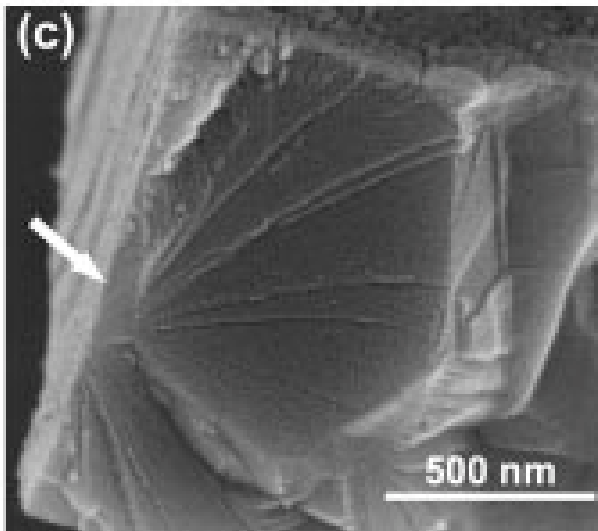
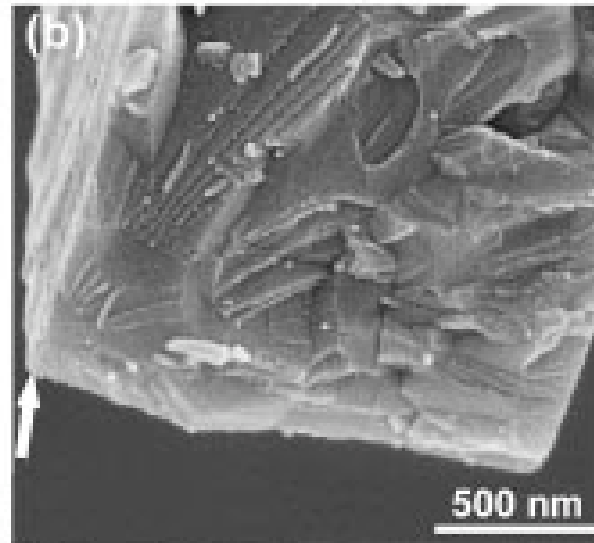
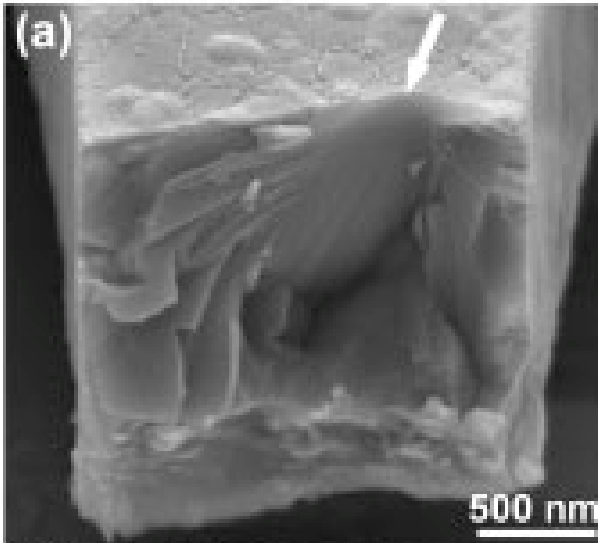


Intermediate Strength



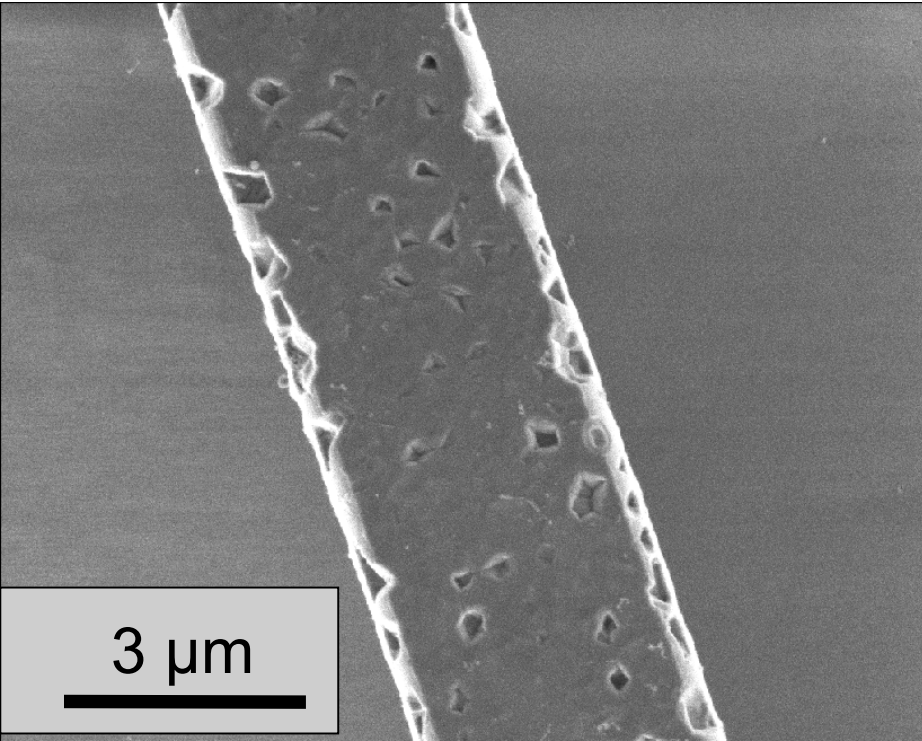
Weakest

Failures Due to Both Etching Flaws (a & c) and Corner Stress Concentrations (b & d)

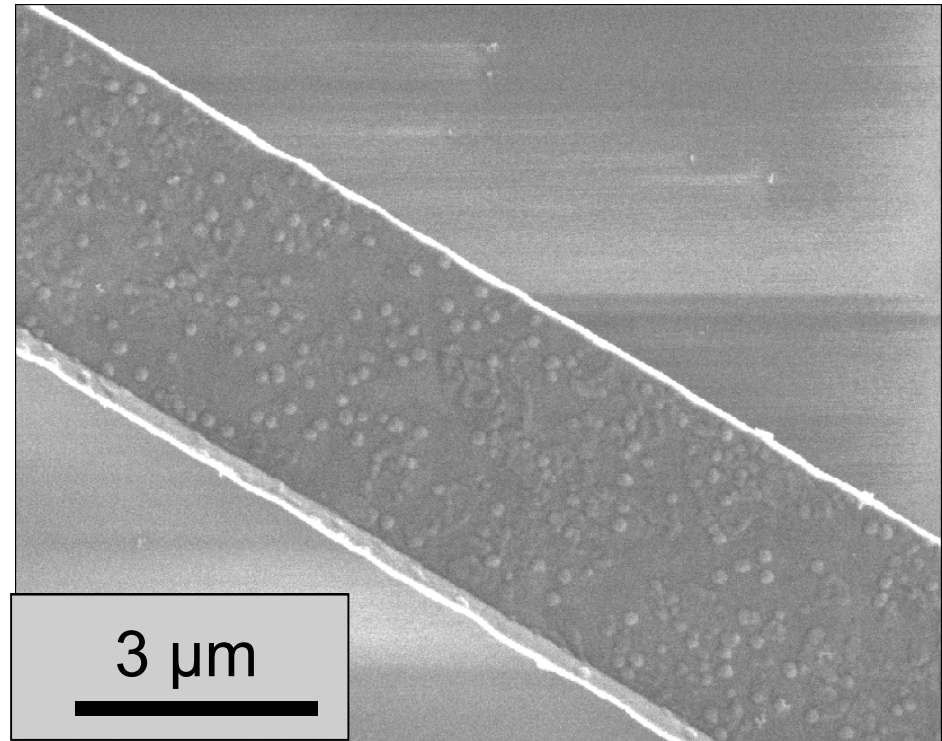


B. Boyce,
Sandia, 2005

Strengths Are Sensitive to Surface Condition (Etching Flaws) for Different Layers

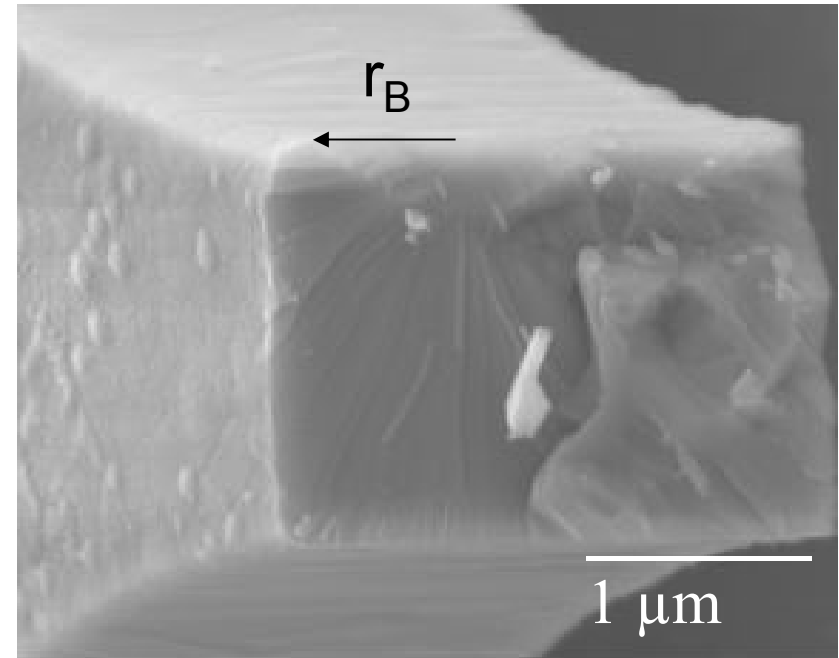
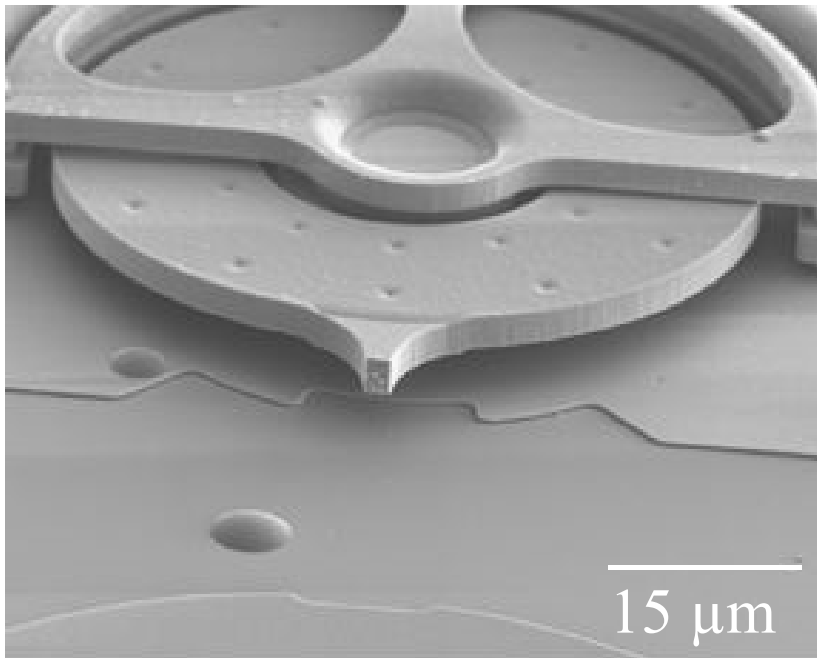


Weak



Strong

Strength Can be Estimated from Fracture Branching Boundaries on Fracture Surface



$$\sigma_f Y r_B^{1/2} = \text{constant} = K_B$$

$$K_B = 2.0 \text{ MPa}\sqrt{\text{m}}$$

(Tsai & Mecholsky, 1992)

$$\text{Therefore, } \sigma_f = 2.1 \text{ GPa}$$



Ingredients for Polysilicon Microelectro-Mechanical Systems (MEMS) Failures

When σ_{applied} > $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$
or residual

Poor Design - Excessive stress

- Excessive applied or **local stress concentrations**
- Materials combinations and/or processing that lead to excessive residual stress

Presence or introduction of defects

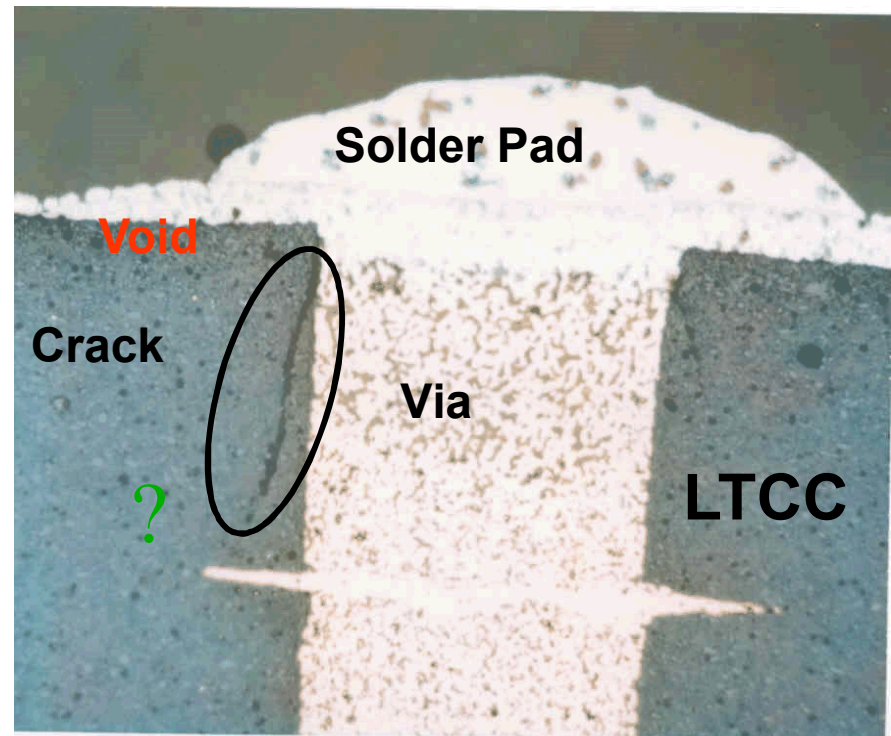
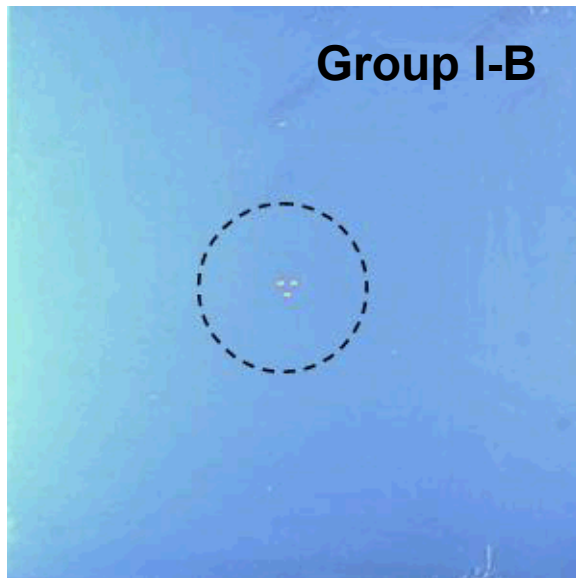
- Intrinsic microstructural features
- ***Processing related***
- Handling or in-service damage

Material degradation (loss of strength)

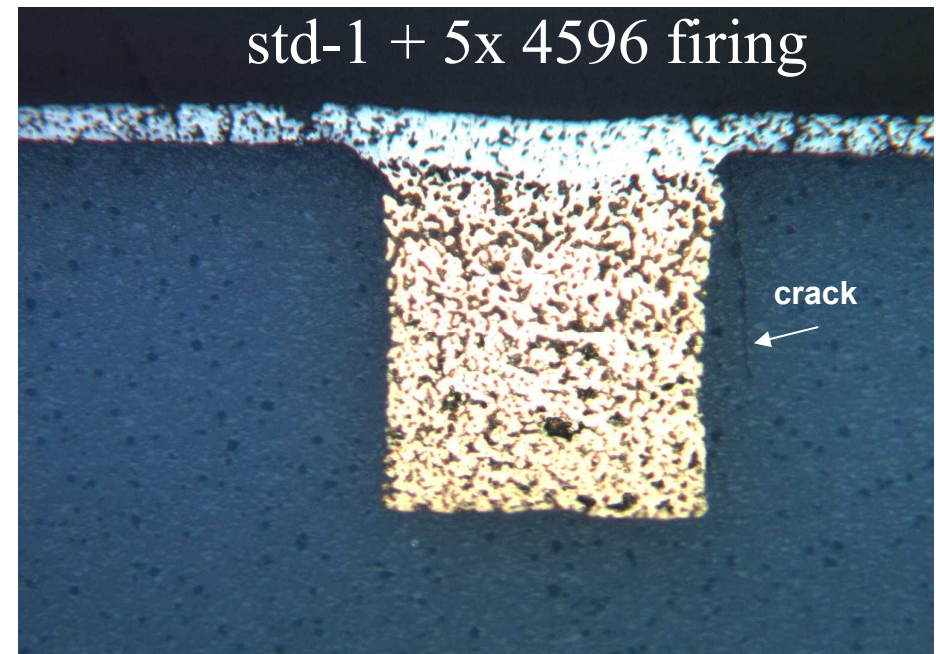
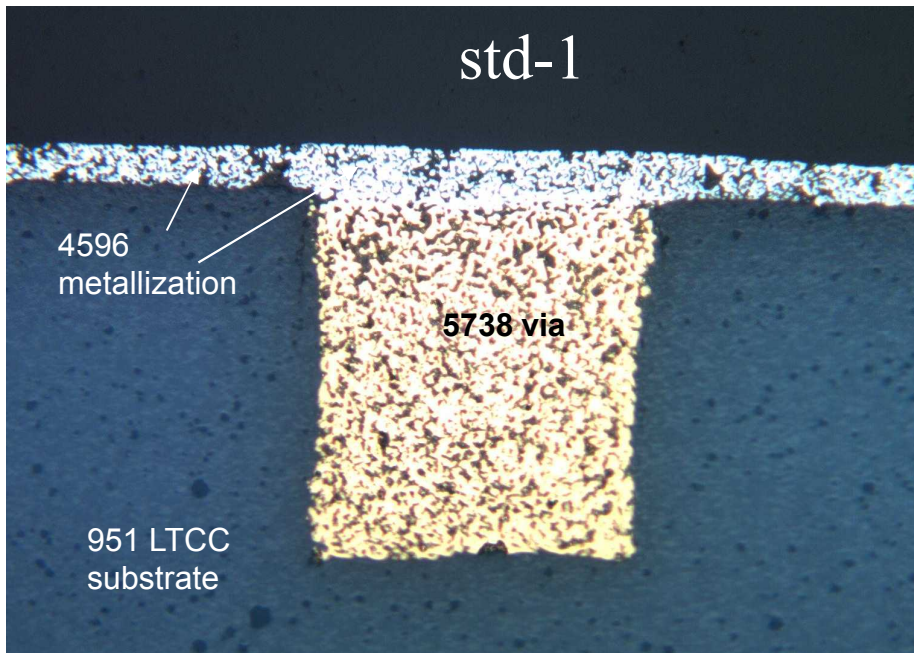
- Environmental effects, decrease in K_{IC}
- Increase in flaw size - subcritical crack growth

Why Does Cracking Occur in the LTCC Near Vias after Metallization and Firing Cycles?

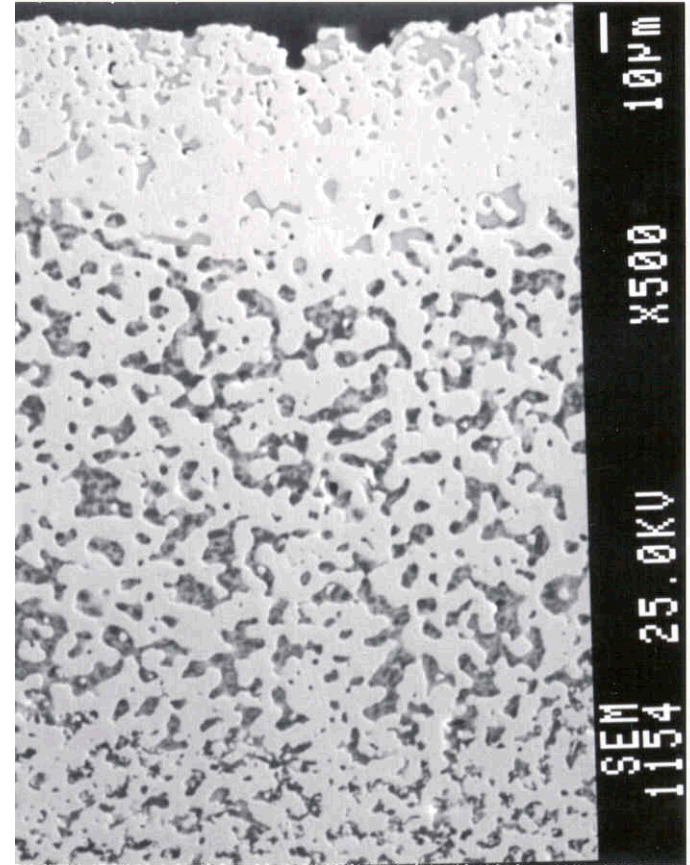
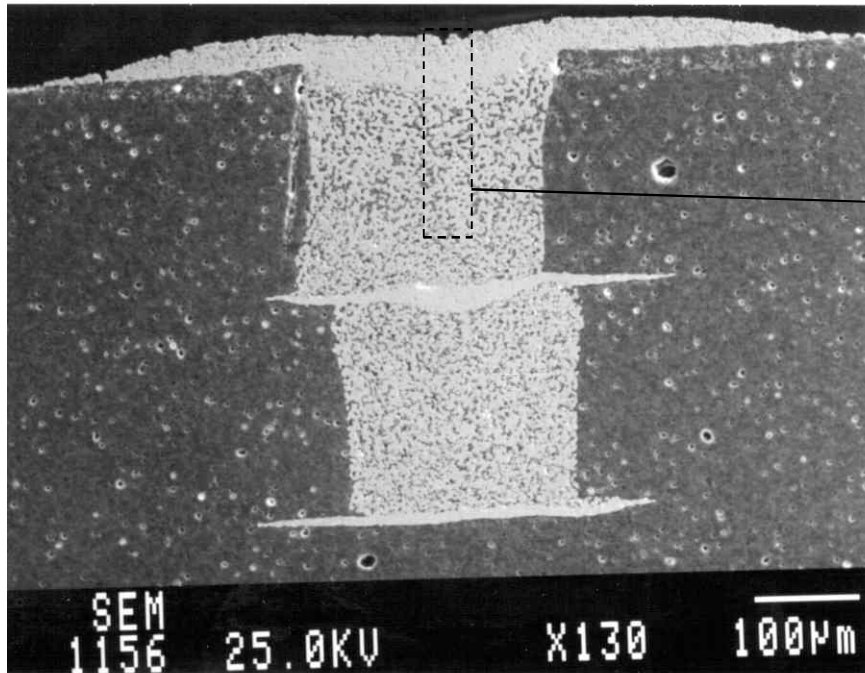
Low temperature co-fired ceramic (LTCC) parts were made with multiple layers of DuPont 951 green tape™ with stacked electrical vias

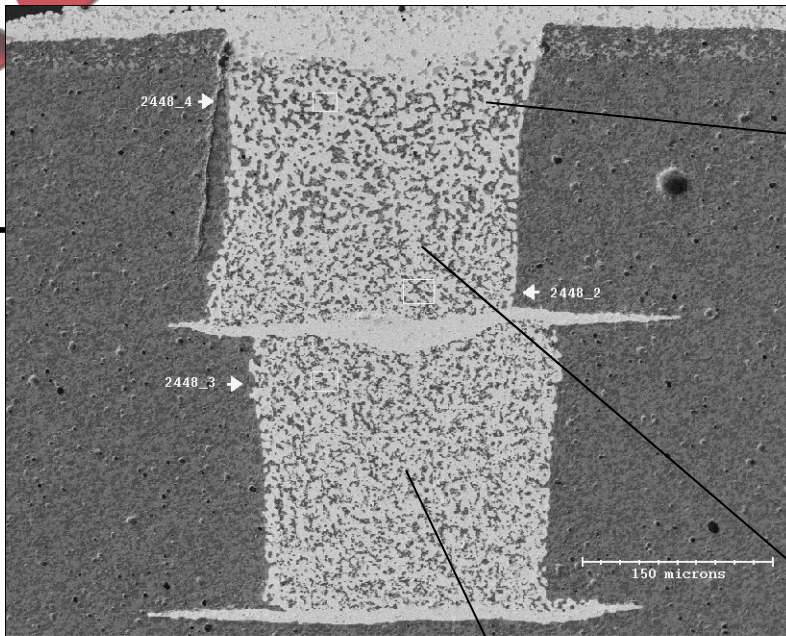
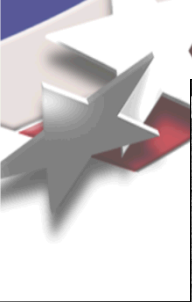


Longitudinal Sections Show LTCC, 5837 Via, and 4596 Metallization

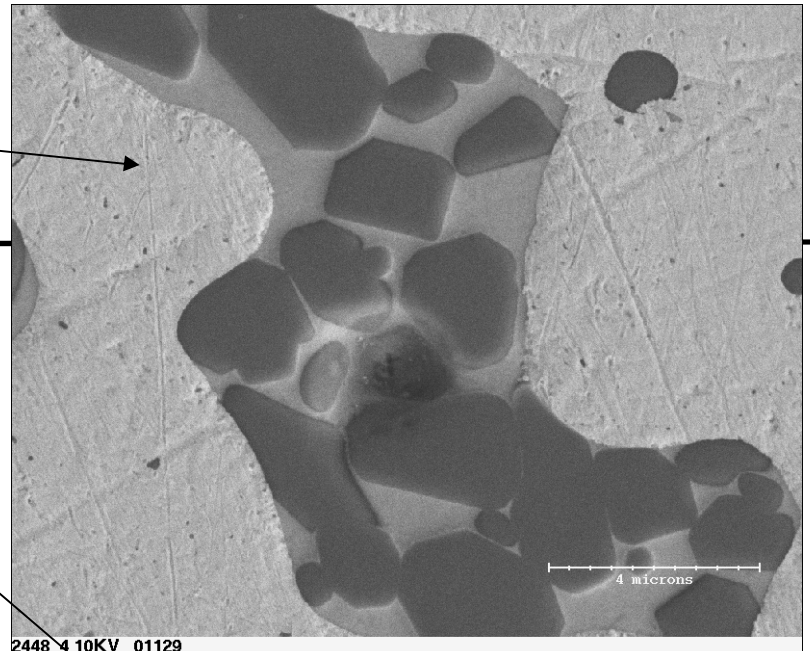


Electron Microprobe Shows Interactions Between Surface Metallization and Via Material

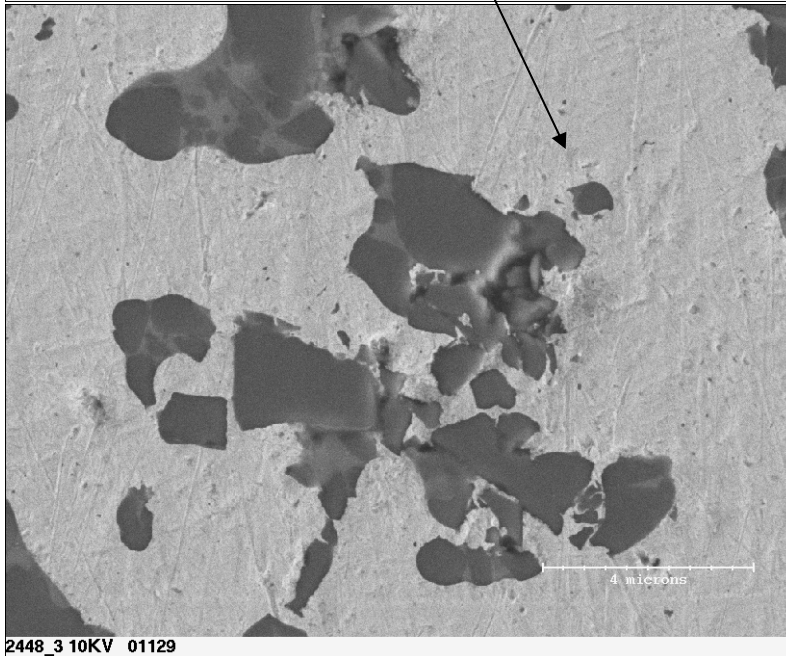




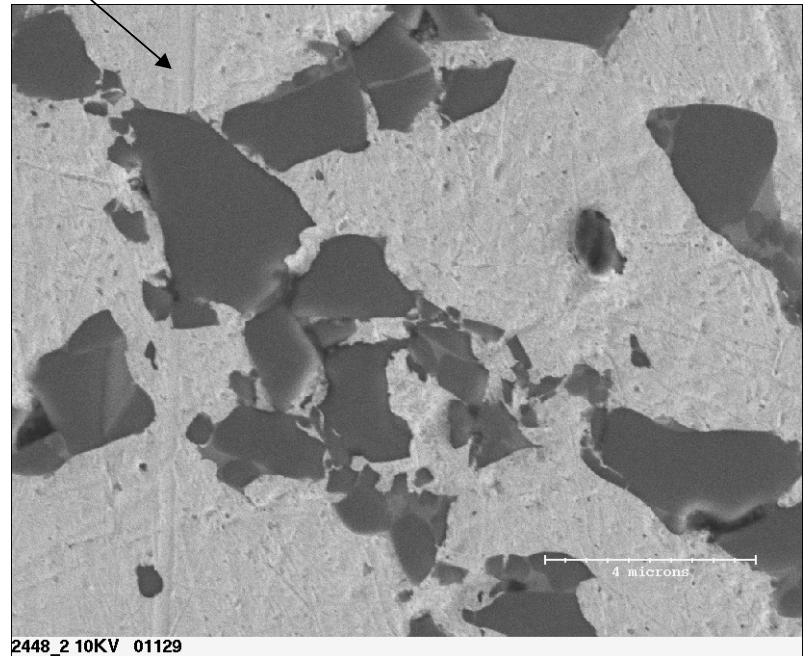
2448_1 10KV 01129



2448_4 10KV 01129

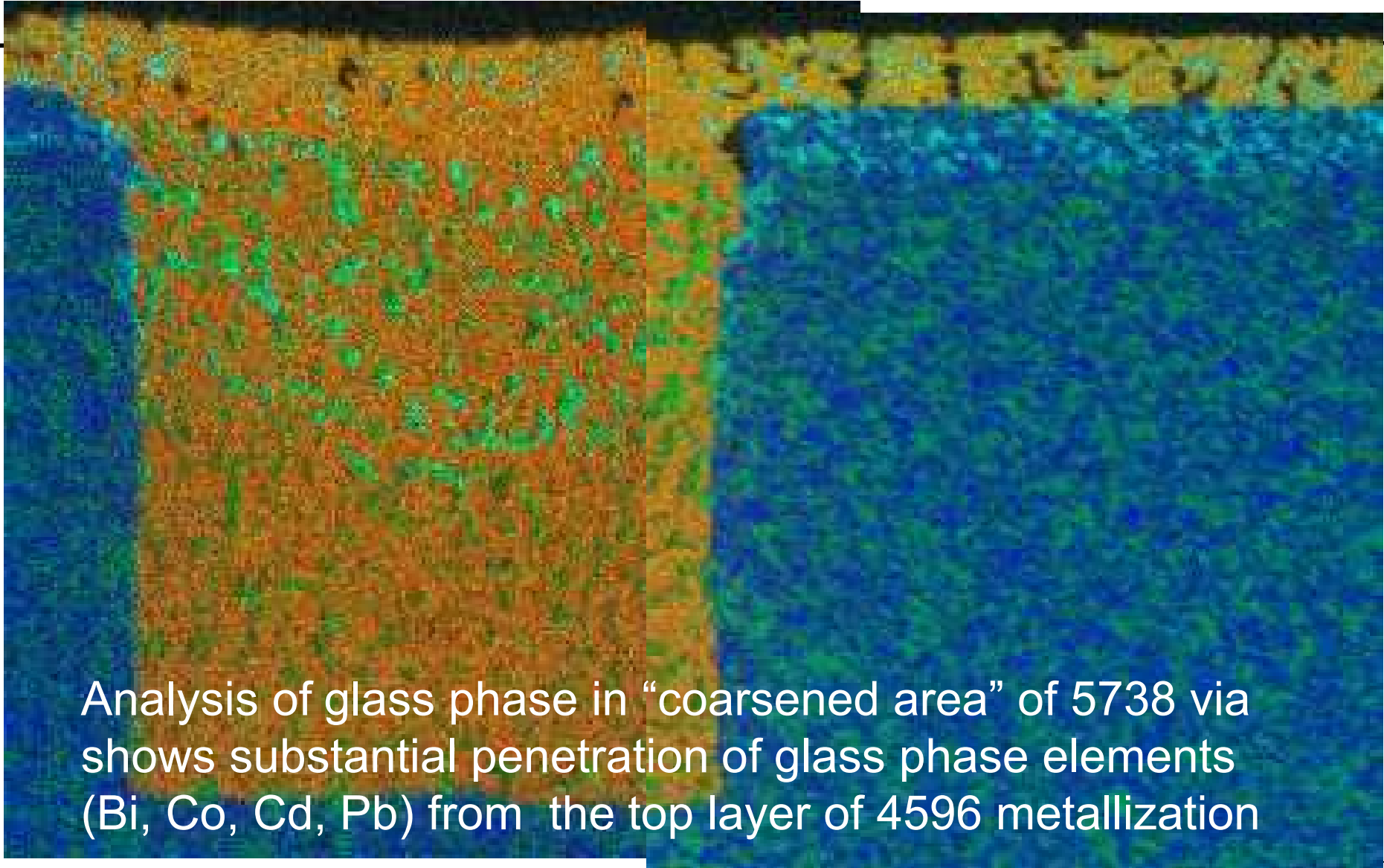


2448_3 10KV 01129



2448_2 10KV 01129

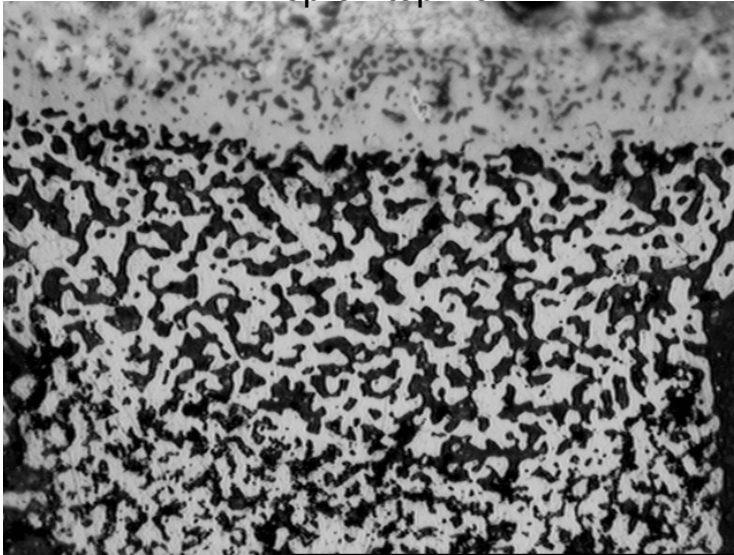
SEM Spectral Image Analysis of Std1_5xFires Parts



Analysis of glass phase in “coarsened area” of 5738 via shows substantial penetration of glass phase elements (Bi, Co, Cd, Pb) from the top layer of 4596 metallization

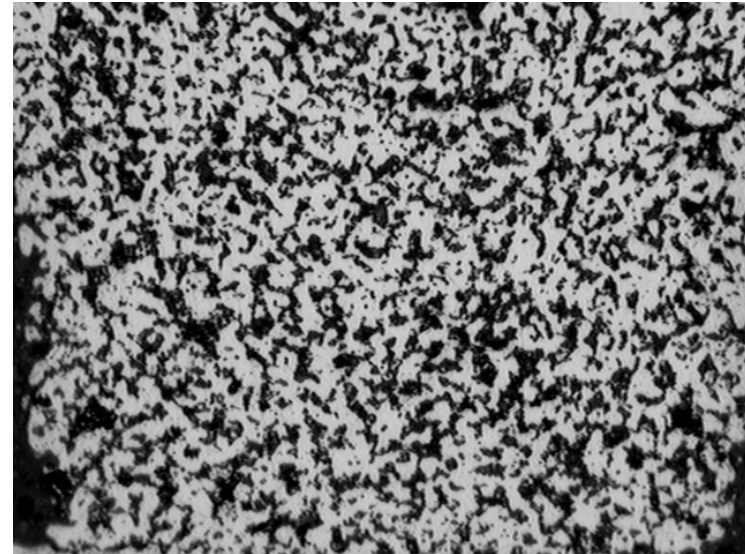
Estimated CTE for Via used in FEA Stress Predictions Based on Original Volume Fractions

Top of top via



area fraction metal= 53%
area fraction other= 47%
MORE Glass than expected

Bottom of top via and internal vias



area fraction metal= 60%
area fraction other= 40%



Ingredients for Failure of a Low Temp Co-Fired Ceramics (LTCCs) with Vias

When σ_{applied} > $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$
or residual

Excessive stress

- Excessive applied stress or macroscopic stress concentrations
- ***Materials combination and/or processing that lead to excessive residual stress***

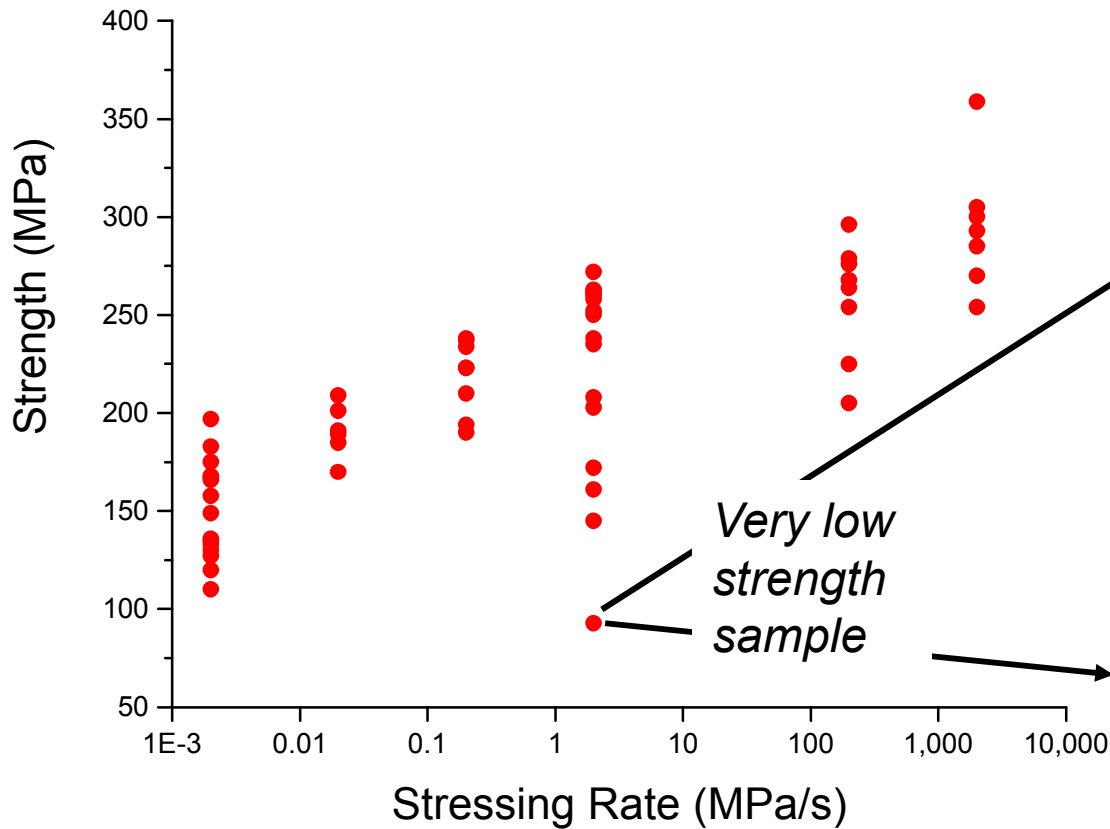
Presence or introduction of defects

- Intrinsic microstructural features
- Processing related
- Machining, in-service damage

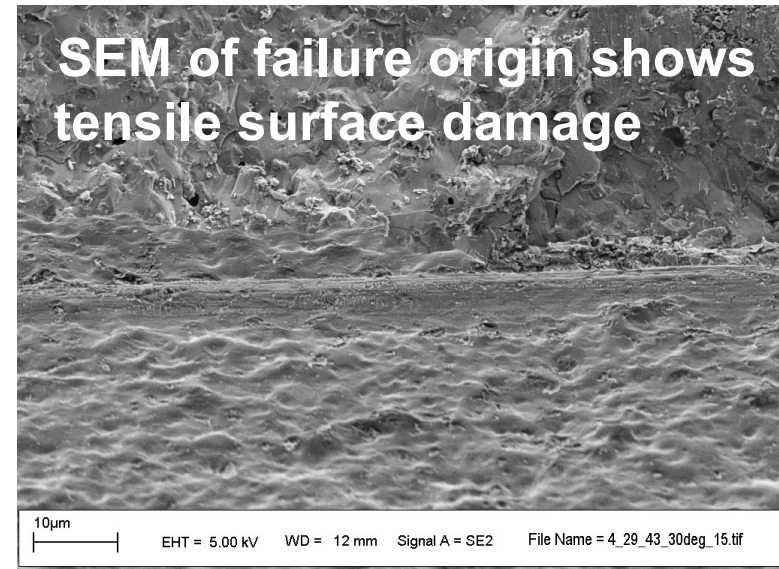
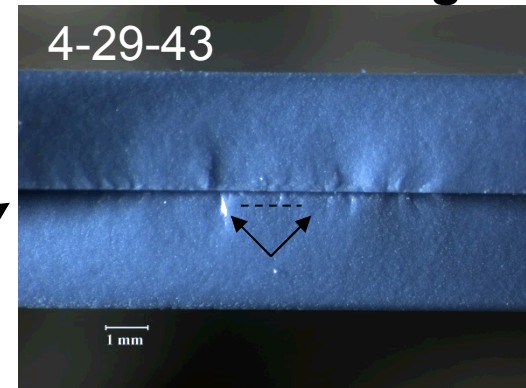
Material degradation (loss of strength)

- Increase in flaw size due to subcritical crack growth
- Decrease in K_{IC}

LTCC Subcritical Crack Growth Data Collected for Lifetime Predictions (crack velocity= AK^n)



Optical exam used to locate failure origin





Ingredients for Failure of Low Temp Co-Fired Ceramic (LTCC) Strength Samples

When σ_{applied} > $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$
or residual

Excessive stress

- Excessive applied stress or macroscopic stress concentrations
- Materials combinations and/or processing that lead to excessive residual stress

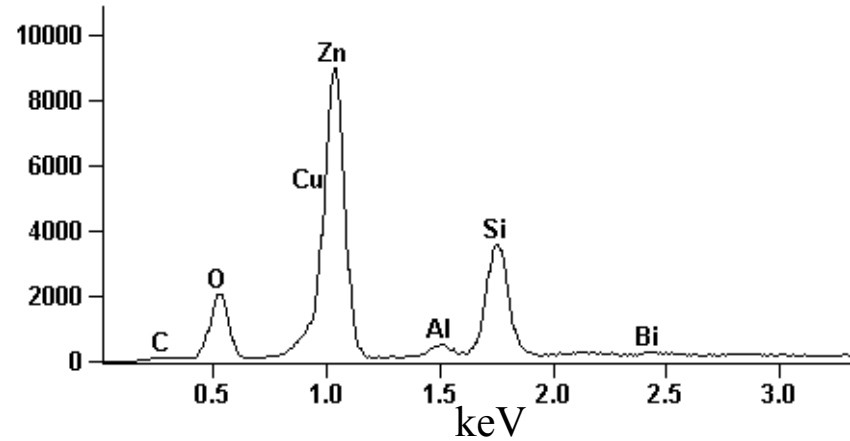
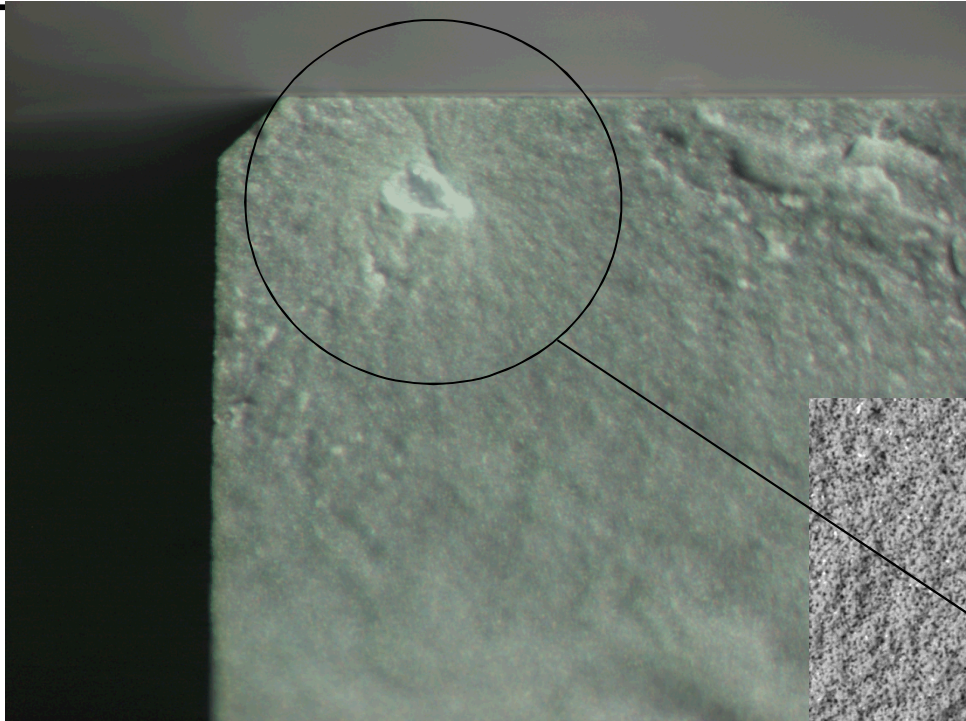
Presence or introduction of defects

- Intrinsic microstructural features
- Processing related
- ***Machining, in-service damage***

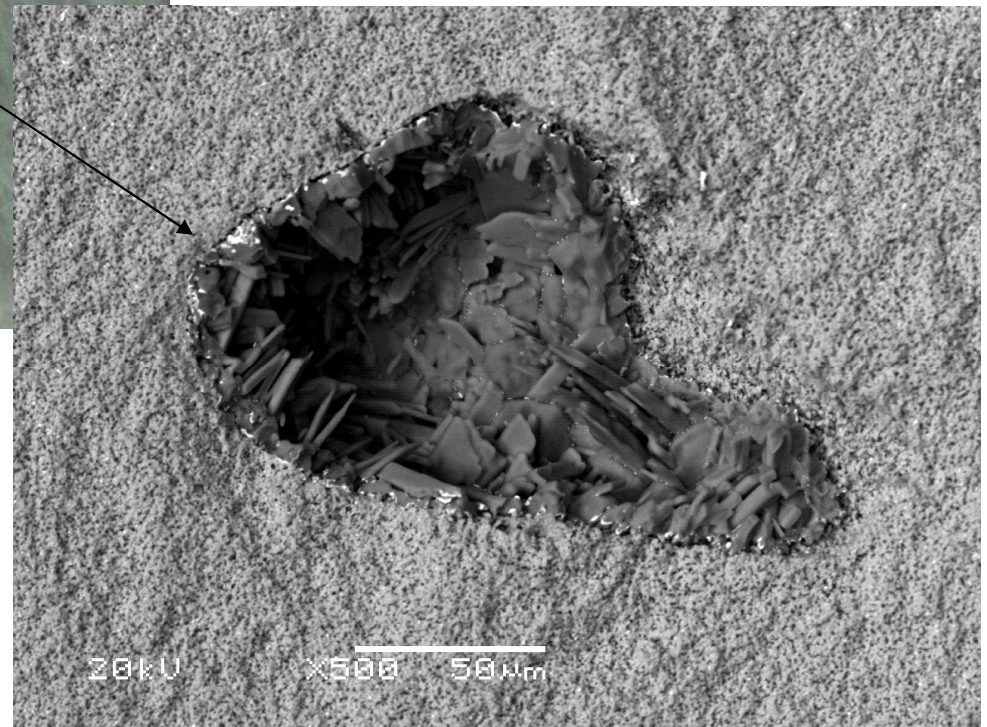
Material degradation (loss of strength)

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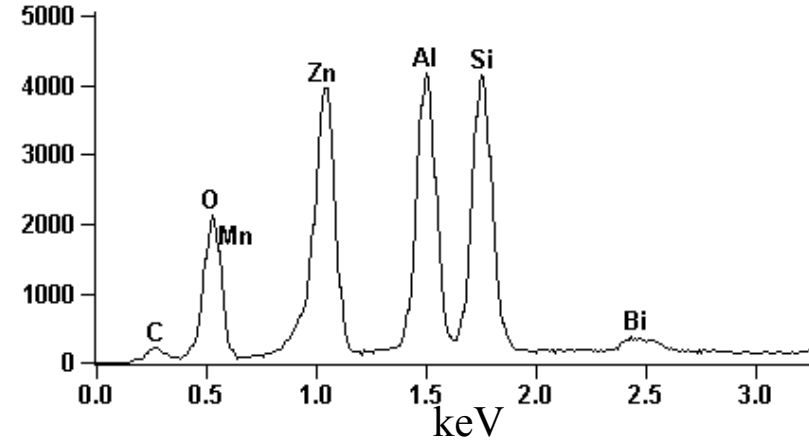
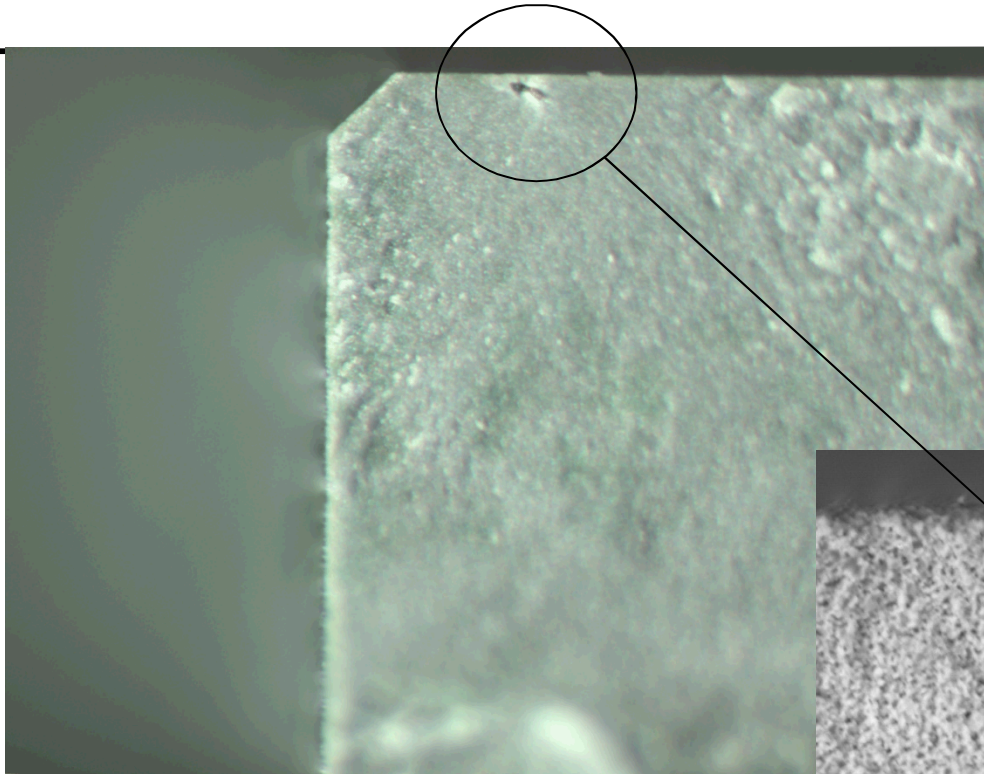
Fractography of ZnO Varistor Bend Bars Reveals that Contaminants Serve as Failure Origins



Si rich inclusion



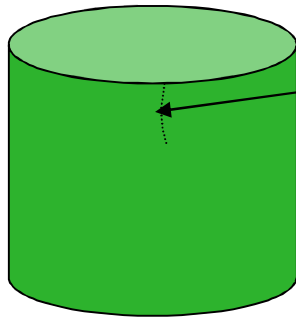
Fractography of ZnO Varistor Bend Bars Reveals that Contaminants Serve as Failure Origins



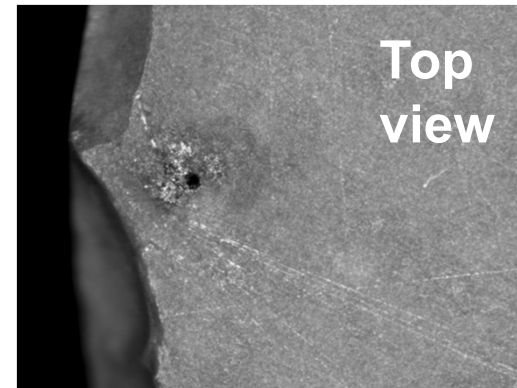
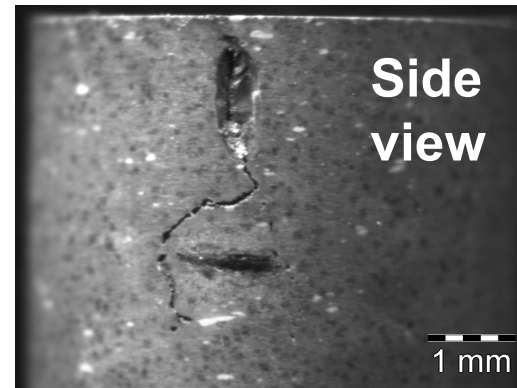
Mn, Al, Si rich inclusion

Surface Damage Studied to Determine How it Contributes to ZnO Electrical Breakdown

Prior to electrical
pulse testing



Crack



- Cracks parallel to current flow produce early breakdowns



Ingredients for ZnO Varistor Failure (Mechanical and Electrical Breakdown Strength)

When σ_{applied} > $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$
or residual

Excessive stress

- Excessive applied stress or macroscopic stress concentrations
- Materials combinations and/or processing that lead to excessive residual stress

Presence or introduction of defects

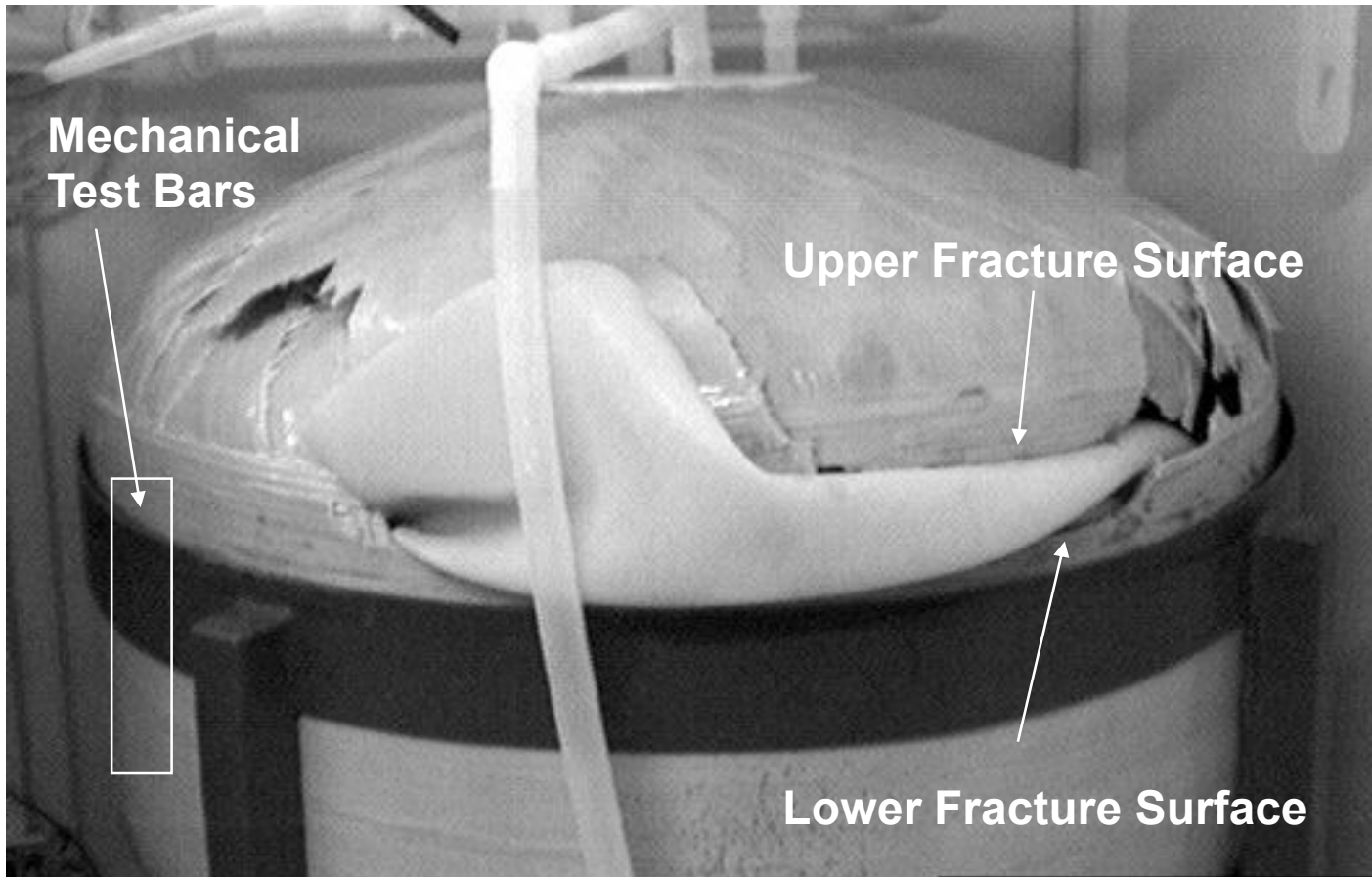
- Intrinsic microstructural features
- ***Processing related***
- ***Machining, in-service damage***

Material degradation (loss of strength)

- Increase in flaw size due to subcritical crack growth
- Decrease in K_{IC}

Failure and Fractography of a Fiberglass Reinforced Composite (FRC) Acid Tank

FRC tank containing sulfuric acid failed catastrophically during a pressurization cycle.





Tank Failure was Due to Several Factors:

- High tensile stress in region of circular wrap just above the constraining cradle
- Cracking of epoxy in circ wraps exposed cross ply fibers
- Sulfuric acid was introduced into the cracks
- Fibers in the cross plies were severely degraded and weakened by acid
- Sequential failure of fibers in cross plies occurred during pressurization cycles until crack of critical dimensions produced
- Catastrophic crack propagation occurred



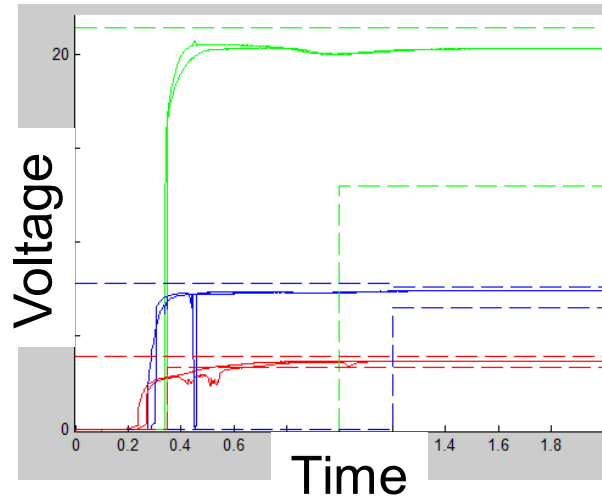
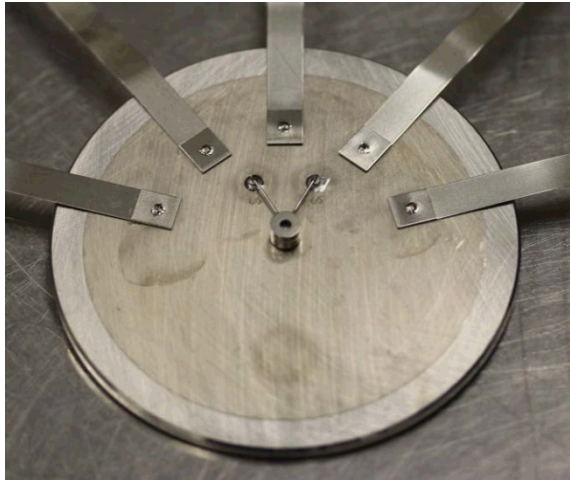
Ingredients for Failure of a Fiberglass Reinforced Composite (FRC) Tank

When σ_{applied} > $\sigma_f = \frac{K_{IC}}{Y\sqrt{c}}$
or residual

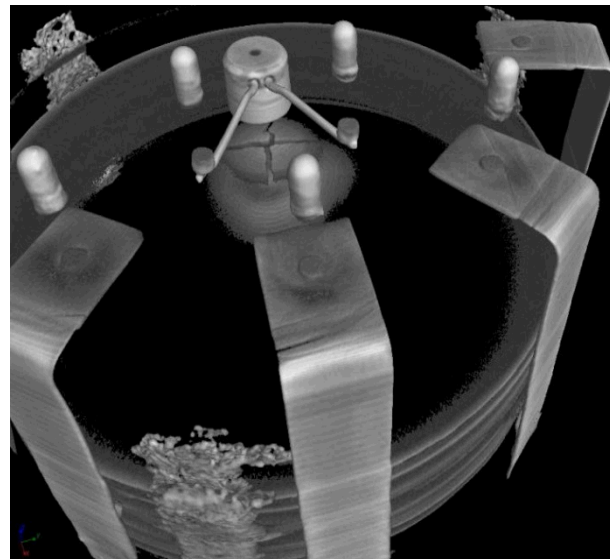
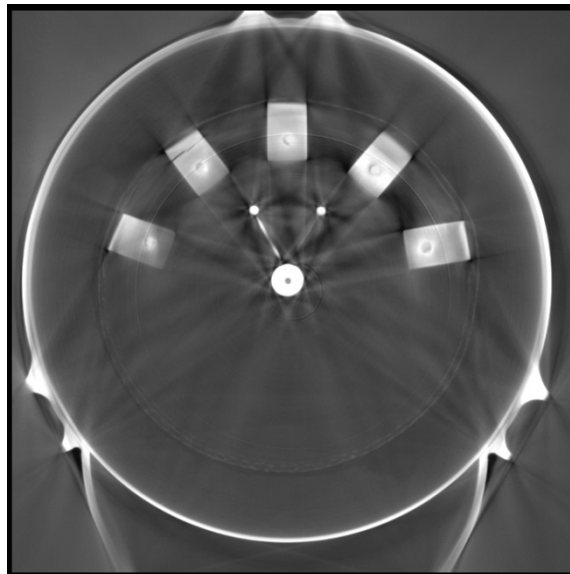
- Excessive stress
 - ***Excessive applied stress or macroscopic stress concentrations***
 - Materials combinations and/or processing that lead to excessive residual stress
- Presence or introduction of defects
 - Intrinsic microstructural features
 - Processing related
 - ***Machining, in-service damage***
- Material degradation (loss of strength)
 - ***Increase in flaw size due to subcritical crack growth***
 - ***Decrease in K_{IC}***

All of the above!

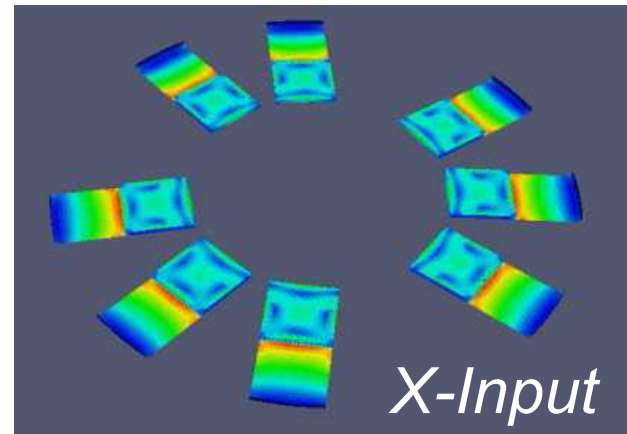
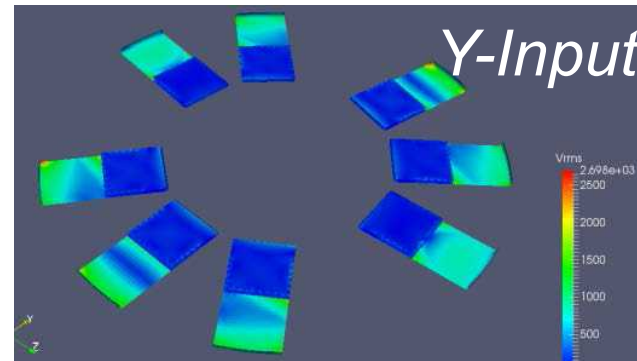
Ni Lead Failures in Thermal Batteries During Testing in Various Vibration Environments



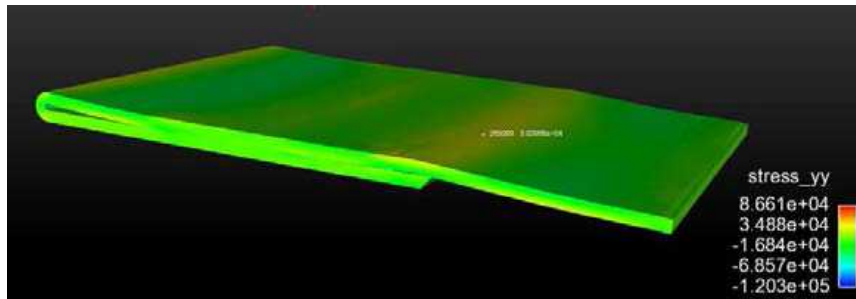
Electrical testing of a thermal battery in a vibration environment showed unacceptable drops in voltage vs. time.



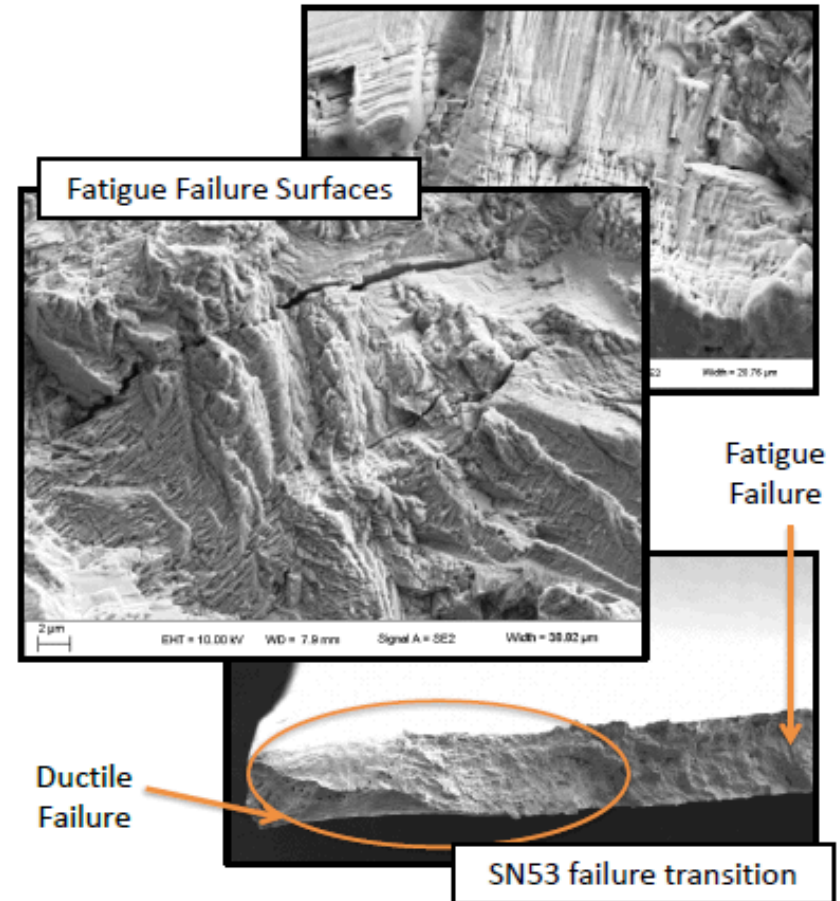
Stress Analyses of Ni Leads For Vibration Tests Showed Stresses were Highly Axis Dependent



Fracture Surface Analysis Confirmed High Cycle Fatigue Failure

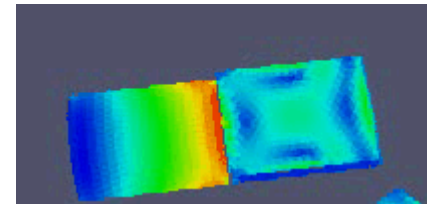


- All three failed Ni leads show surface that appears brittle, with tightly spaced striations throughout
- Based on these features, failures are consistent with low amplitude, high cycle fatigue (transportation vibration environment)
- Remainder of lead was 'failed' in lab environment – portion exhibited ductile failure as expected for Ni 201



Ingredients for the Failure of a Battery Lead

- Design - Excessive stress
 - **Excessive applied stress/macroscopic stress concentrations**
 - Materials combinations and/or processing that lead to excessive residual stress
- Presence or introduction of defects
 - Intrinsic microstructural features
 - **Processing related defects**
 - Machining, in-service damage
- Material degradation (loss of strength)
 - **Increase in flaw size due to fatigue crack growth**
 - Decrease in K_{IC}





Making the Most of Our Failures

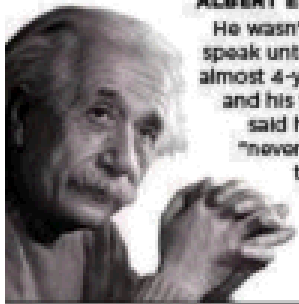
- Failure/survival depends on properties, flaws, design - loading (applied and residual), and environment
- Failure often due to a combination of factors
- We have valuable opportunities to improve our materials, processing, designs, and analyses by “*observing, measuring, and interpreting our failures*” (D. Hull)

Materials Failure Experiences as a Metaphor for Human Failure

FAMOUS FAILURES

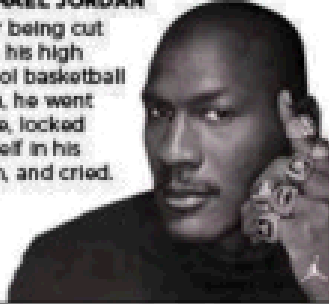
ALBERT EINSTEIN

He wasn't able to speak until he was almost 4-years-old and his teachers said he would "never amount to much"



MICHAEL JORDAN

After being cut from his high school basketball team, he went home, locked himself in his room, and cried.



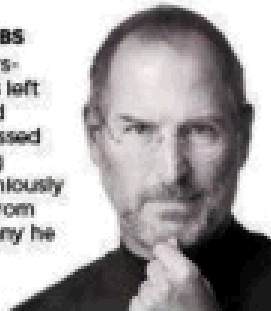
WALT DISNEY

Fired from a newspaper for "lacking imagination" and "having no original ideas."



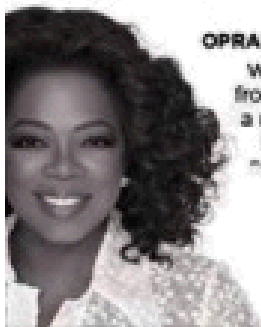
STEVE JOBS

At 30-years-old he was left devastated and depressed after being unceremoniously removed from the company he started.



OPRAH WINFREY

Was demoted from her job as a news anchor because she "wasn't fit for television."



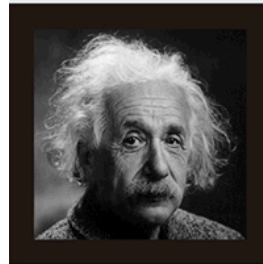
THE BEATLES

Rejected by Decca Recording Studios, who said "We don't like their sound—they have no future in show business."



104 TIMES

Albert Einstein didn't speak until he was four and didn't read till seven. He went on to win a Nobel Prize and became the face of modern physics.



12 TIMES

J.K. Rowling was famously rejected by a mighty 12 publishers before Harry Potter and The Philosopher's Stone was accepted.



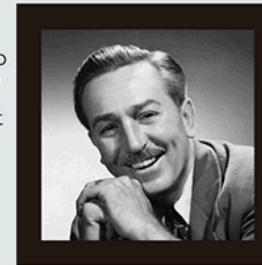
27 TIMES

Dr. Seuss's first book To Think That I Saw It on Mulberry Street was rejected by 27 different publishers.



302 TIMES

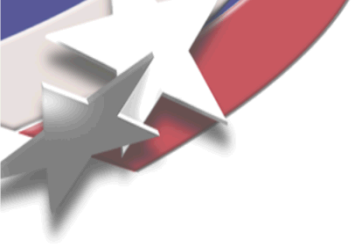
Legend has it Walt Disney was turned down 302 times before he got financing for creating Disneyland.





Acknowledgments

- Penn State – Dr. David Green, Dr. Gary Messing, Dr. Richard Tressler, Dr. John Hellman, Dr. Jack Mecholsky (U. of Florida), and many others
- Sandia Colleagues - Ed Beauchamp, Brad Boyce, Tom Buchheit, Bonnie McKenzie, Sandy Monroe, Clay Newton, Christine Roth, Rajan Tandon, Chad Watson, Eric Tumilowicz, Richard Heller, Henry Padilla, Louie Cano, David Enos, Don Susan, Joe Romero, Environmental Testing Lab colleagues, and many others



Thank you!



Failure Quotes

“Materials are a lot like people, imperfections control their behavior” Rusty Gray

“All major weaknesses have been exposed, analyzed, and replaced with new weaknesses.” Bruce Leverett

**Failure is not an option. It comes bundled with your software.
Unattributed**



Back-Up Slides

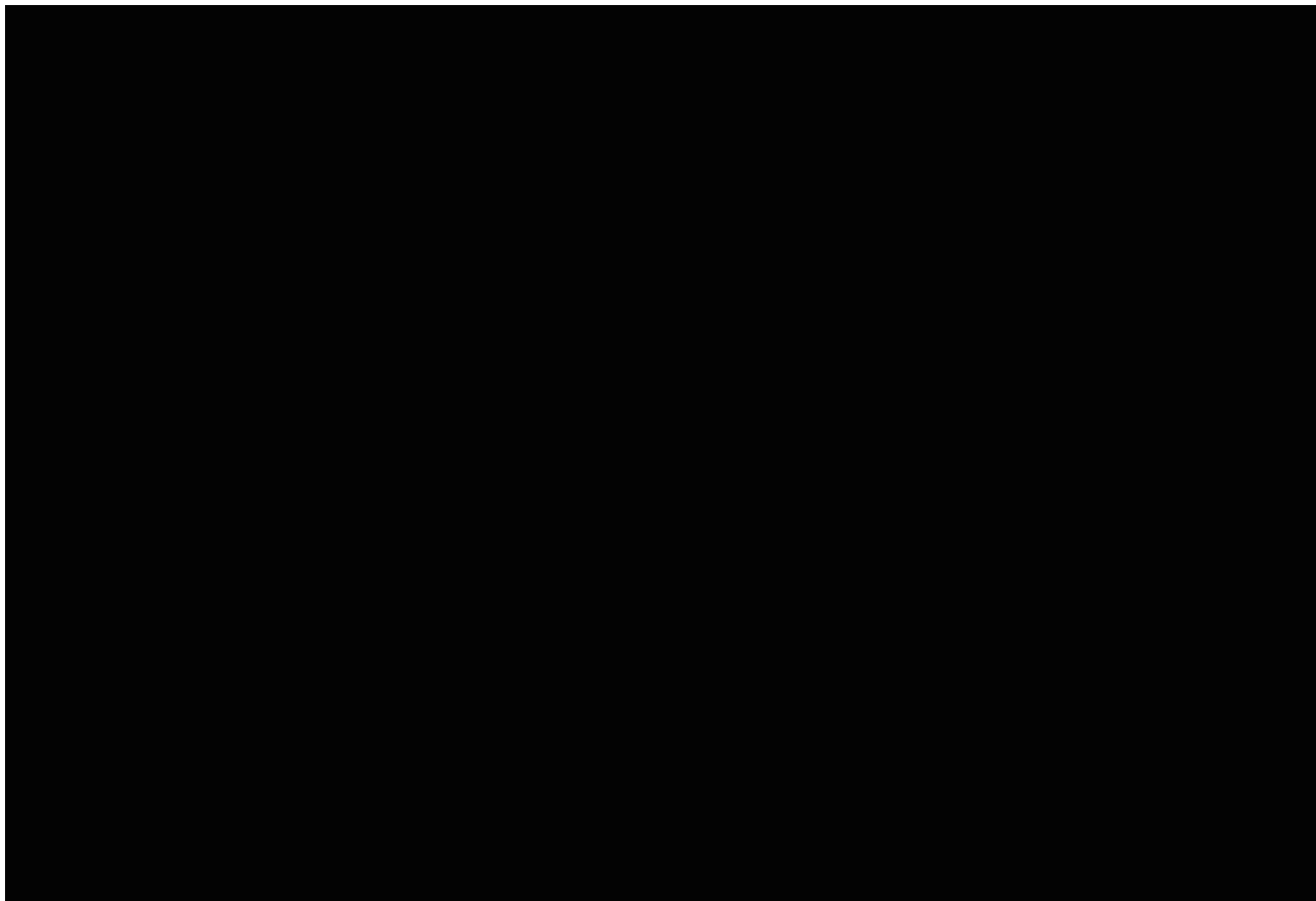


“Safety Movie”





Glass Failure Movie



Optical Examination Revealed Unusually Flat Fracture Surfaces

- Few fibers protruded from fracture surfaces of failed tank

